

GOODiX



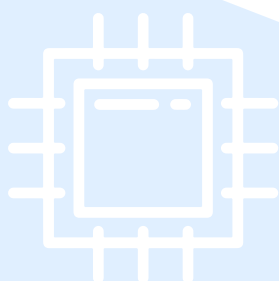
2024 Annual Report Summary

Shenzhen Goodix Technology Co., Ltd.

603160.SH

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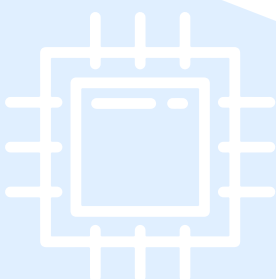
About Goodix

Goodix Technology (SH: 603160) is an integrated solution provider for applications based on IC design and software development, focusing on four core technological categories—sensing, AI processing, connectivity, and security. It provides industry-leading software and hardware semiconductor solutions for smart devices, automotive electronics, and IoT applications. Goodix serves hundreds of millions of global consumers with quality products and solutions via renowned brands including Samsung, Google, Amazon, Dell, Huawei, OPPO, vivo, Xiaomi, Honor, Lenovo, Transsion, BYD, Hongqi, Geely, GAC, Buick, Honda, Toyota, Nissan, NIO, XPeng. The Company is recognized as a leading IC design and solution provider that empowers a connected, intelligent world.

As a key player in the global semiconductor industry, Goodix continues its dedication in research and development, striving to establish the comprehensive IC design portfolio for smart devices, automotive

electronics, and IoT applications, with the goal of becoming a world-leading comprehensive IC design company. By delivering cutting-edge solutions that consistently exceed expectations, the Company offers long-term and differentiated values to the industry and the society, and provides excellent career development opportunities for Goodix's global talents.

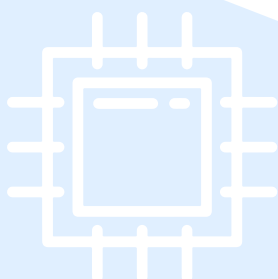
Goodix adopts the fabless model, and focuses on the IC design, research&development and sales, while outsourcing tasks such as wafer manufacturing, packaging, and testing to professional wafer foundries and packaging/testing providers. The products Goodix offers are sold both directly as well as via agents and distributors to customers. Combining these two sales methods significantly reduces customer acquisition costs, mitigates accounts receivable risks, and enhances operational efficiency and market responsiveness.



Key Figures

Unit: M RMB	2024	2023	YoY Change (%)
Revenue	4,374.9	4,408.1	-0.8
Gross margin (%)	41.8	40.5	1.3
Operating profit	667.8	80.4	730.7
Operating margin (%)	15.3	1.8	13.4
Net profit	603.7	165.1	265.8
R&D expense	950.0	1,049.3	-9.5
Net profit attributable to shareholders of the Company	603.7	165.1	265.8
Net profit attributable to shareholders of the Company excluding non-recurring gains and losses	558.1	132.1	322.3
Net cash flows from operating activities	1,072.7	1,785.8	-39.9
Basic earnings per share (RMB/share)	1.3	0.4	269.4
Diluted earnings per share	1.3	0.4	266.7
Weighted average ROE(%)	7.3	2.1	5.2

	At December 31 2024	At December 31 2023	YoY Change (%)
Total assets	10,304.3	9,727.0	5.9
Cash and short-term investments	4,784.4	4,021.4	19.0
Net assets attributable to shareholders of the Company	8,721.5	8,045.3	8.4
Stockholders' equity	8,721.5	8,045.3	8.4
Debt ratio (%)	15.4	17.3	-1.9



1. Analysis of Business Operations

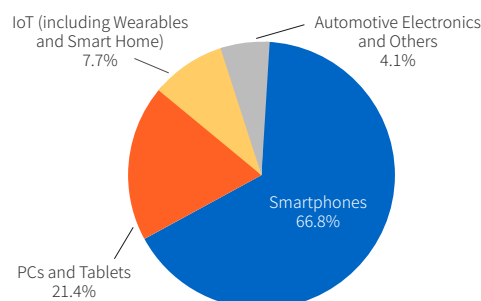
The Company is an integrated solution provider for applications based on IC design and software development, focusing on core technologies including sensing, AI processing, connectivity, and security. By developing innovative solutions that enable an intelligent and connected world, the Company targets the smart devices, IoT, and automotive electronics markets.

In the smartphone market, the Company offers a comprehensive product portfolio that includes fingerprint sensors, touch solutions, active stylus solutions, audio products, in-display light sensors, and NFC/eSE chips. The innovations have been widely adopted by leading smartphone brands, enhancing the product value of each smartphone unit. In the PC and tablet sectors, the Company also provides a diverse range of products, such as fingerprint sensors, touch solutions, touchpad solutions, active stylus solutions, audio products, and in-display light sensors. In IoT segment such as smart wearables, the Company delivers a broad array of offerings, including health sensors, Bluetooth Low Energy (BLE) SoC products, in-display light sensors, touch solutions, and audio products, addressing varied application scenarios and serving a diversified customer base. Additionally, in the automotive electronics, the Company provides automotive-grade touch solutions, fingerprint sensors, audio software, and automotive-grade BLE SoC products. With a rich product portfolio and extensive application scenarios, the Company has established a robust foundation for further product promotion and increased market recognition.

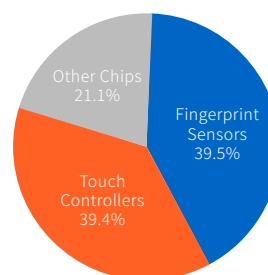
During the reporting period, the Company reported total revenue of RMB 4,374.95 million, a year-on-year decrease of 0.75%. Operating costs amounted to RMB 2,546.54 million, a reduction of 2.97% compared to the same period of the previous year. The overall gross profit margin increased by 1.33 percentage points year-on-year.

Revenue Breakdown by Major Application

Fields in 2024

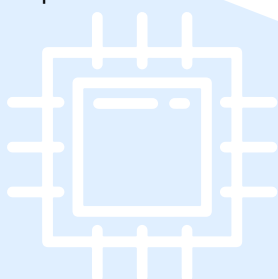


Revenue Breakdown of Principal Businesses in 2024



(1) Significant Improvement in Profitability

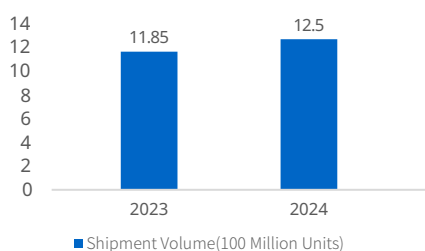
During the reporting period, the net profit attributable to shareholders of the listed company reached RMB 604 million, representing a year-on-year increase of 265.8%, reflecting a significant improvement in profitability. The primary factors influencing this performance are outlined as follows:



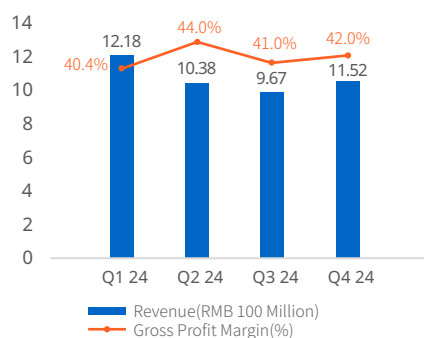
1) Increasing market demand, successive commercialization of new products, and the rapid adoption of OLED display contributed to a total shipment volume of 1.25 billion units, representing a year-on-year growth of 5.5%. However, due to market dynamics and competitive pressures, the Company experienced a decline in its average selling price (ASP), resulting in revenue of RMB 4.375 billion, down by 0.8% year-on-year.

2) The gross profit margin improved from 40.5% to 41.8%, driven by reductions in chip procurement costs and positive impacts derived from product iterations of existing products.

Shipment Volume in 2024 vs 2023



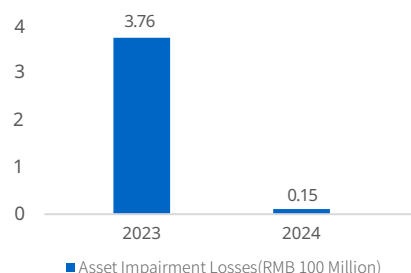
Quarterly Revenue and Gross Profit Margin in 2024



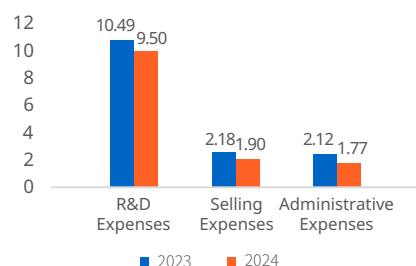
3) The Company strengthened its asset management, resulting in no significant asset impairment losses during the reporting period.

4) Through focused improvement in R&D efficiency and cost optimization of selling and administrative expenses, the Company achieved a year-on-year reduction of RMB 161 million (a decline of 10.9%) in combined selling, general and administrative (SG&A) and R&D expenses.

Asset Impairment Losses in 2024 vs 2023

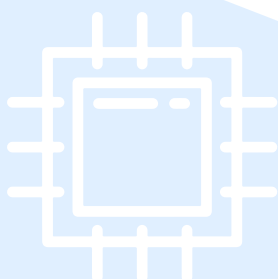


Selling, Administrative and R&D Expenses in 2024 vs 2023 (RMB 100 Million)

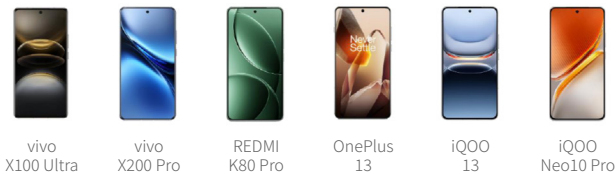


(2) Large-scale Commercial Adoption of the Company's New Products

1) The Company's ultrasonic fingerprint sensors have achieved large-scale commercial adoption among leading smartphone brands, including vivo, Xiaomi, iQOO, REDMI, and OnePlus, with annual shipments exceeding 8 million units. These sensors have been integrated into premium flagship models, such as vivo X100 Ultra, vivo X200 Pro, and OnePlus 13, as well as mid-to-high-end models like the REDMI K80 Pro and iQOO Neo10 Pro. The industry's shift toward



low-transmittance displays is expected to further boost the penetration of ultrasonic fingerprint sensors in smartphones.



2) The Company's new-generation in-display light sensors have achieved wide commercialization in premium flagship smartphone models such as the vivo X200 and iQOO 13 series, with annual shipments reaching 5 million units. Beyond smartphone applications, the Company's light sensors have also been applied on renowned projector products such as the JMGO N1S series and O2 Ultra, as well as Lenovo Legion Y900 tablets. With core advantages including high performance, low power consumption, ultra-short exposure time, high integration levels, and cost-effectiveness, these solutions are expected to achieve broader commercialization across a wider range of OLED-equipped end devices in the future.



3) The Company's NFC/eSE solutions have successfully achieved large-scale shipments in smartphone models of leading brands, with annual shipments reaching approximately 3 million units. The NFC products feature outstanding RF performance and compatibility, while the security chips have obtained prestigious certifications, including SOGIS CC EAL 6+, OSCCA L2 Certification (the highest domestic security level for commercial use), and NPTC (National Financial Technology

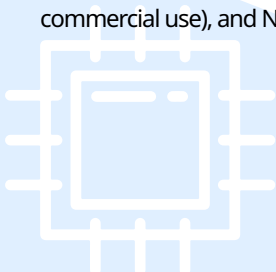
Certification). The Company is currently expanding the adoption of these solutions into a wider range of smartphone brands. Driven by the growing popularity of the Alipay's "Tap-to-Pay" feature, the usage frequency of NFC in China has steadily risen, creating a favorable environment to boost the penetration rate of NFC in smartphones. This trend is expected to generate more commercial opportunities for the Company's NFC/eSE product offerings.

(3) Continuous Improvement in Operating Efficiency

During the reporting period, the Company enhanced its internal management by effectively keeping inventory at a reasonable level while ensuring timely product deliveries. As of the end of 2024, the carrying value of the Company's inventories reached RMB 570 million, representing a decrease of 20.4% from RMB 716 million at year-end 2023. Inventory turnover significantly improved from 2.1 times to 4.0 times, demonstrating substantial enhancements in operating efficiency.

(4) The Company Divests 100% Equity Stake in Its Wholly-Owned Sub-Subsidiaries

In alignment with the Company's strategic development roadmap and adjusted business layout plans, the Company transferred the 100% equity stake in DCT GmbH and DCT B.V.—both held by its wholly-owned subsidiary Goodix (Hong Kong)—to Tessolve Engineering Service Pte. Ltd. This strategic move aims to optimize resource allocation and further enhance core competitiveness of the Company. The initial transaction consideration for this equity transfer was EUR 42.5 million. The equity transfer was successfully completed in February 2025.



2. Industry Overview During the Reporting Period

(1) Industry Development Conditions

In 2024, the global semiconductor industry has shown a steady recovery. According to the Semiconductor Industry Association (SIA), global semiconductor sales reached USD 627.6 billion in 2024, representing a year-on-year increase of 19.1% compared to 2023. Additionally, double-digit growth is expected to continue in 2025. Analyzing by region, semiconductor sales in the Americas, China, and Asia-Pacific regions in 2024 grew by 44.8%, 18.3%, and 12.5% year-on-year respectively, while Japan and Europe experienced decreases of 0.4% and 8.1%, respectively. Driven by increasing demand for AI and high-performance computing, markets for cloud data centers, terminal devices, and specific industrial applications will undergo specifications upgrading, which is expected to further accelerate semiconductor sales growth.

(2) Industry Development Conditions in the Company's Major Application Fields

1) Smart Device Segment

Smartphones: The smartphone market experienced several notable shifts in 2024:

a) Rising OLED Penetration: According to Omdia, the penetration rate of OLED smartphones globally increased steadily, reaching 55% in 2024, with a total of 661 million units shipped. As the Company's ultrasonic fingerprint sensors, optical in-display fingerprint sensors, touch solutions, and in-display light sensors are primarily adopted in OLED smartphones, the increasing OLED market share presents greater market opportunities for the Company's products.

b) Increasing Popularity of AI Smartphones: AI-enabled smartphones have increasingly gained scale, becoming a significant driver in the smartphone market while simultaneously raising the requirements for device specifications and security features. c) Foldable Smartphone Continued High Growth: Shipments of foldable smartphones recorded notable growth, benefiting the Company's touch and active stylus solutions. IDC forecasts indicate foldable smartphone shipments in China would reach approximately 9.17 million units in 2024, up by 30.8% year-on-year. Driven by the increased demand and structural transformations highlighted above, shipments of the Company's products including fingerprint sensors, touch solutions, audio products, in-display light sensors, and NFC/eSE products are expected to achieve varying degrees of growth in 2024.

PC: In 2024, propelled by increased AI penetration and accelerated digital transformation, application scenarios for PCs have continued to expand. Alongside subsidy policies in China and promotional activities overseas, replacement demand for PCs has been effectively stimulated, leading to a modest rebound in the traditional PC market. According to IDC, global PC shipments reached 263 million units in 2024—representing a year-on-year increase of 1% and marking the first growth after three consecutive years of decline.

Meanwhile, as AI technologies have become increasingly widespread, the penetration rate of AI-enabled PCs in China is projected to rise significantly



from 8.1% in 2023 to 84.6% by 2028, signifying enormous potential. Tablet Market: According to Canalys, global tablet shipments in 2024 reached 148 million units, an increase of 9.2% year-on-year, demonstrating a steady recovery trend. The growth in both PC and tablet markets is expected to stimulate shipments of the Company's products, such as fingerprint sensors, touch solutions, Touchpad solutions, in-display light sensors, and audio products.

2) IoT Sector

With the accelerating adoption of AI technologies, the IoT ecosystem continues to expand rapidly. AI-enabled terminal devices are increasingly being applied across diverse scenarios, including smart home, automotive, healthcare, manufacturing, agriculture, and energy industries, thus driving sustained growth in market demand.

Smart wristband devices—primarily smart watches and fitness bands—represent an important IoT market segment. According to Canalys, global wrist-wearable device shipments reached 193 million units in 2024, up 4% year-on-year, marking the second consecutive year of growth following the market adjustment in 2022 and demonstrating clear recovery momentum. Strong demand from China and emerging markets has become a primary growth driver, offsetting declining trends in mature markets such as the United States and India. Benefiting from rising demand by top-tier brand customers, China remained the world's largest wrist-wearable device market, accounting for 30% of global shipments in 2024 and representing a year-on-year growth of 20%. This rapid growth in China's wrist-wearable device market has opened up

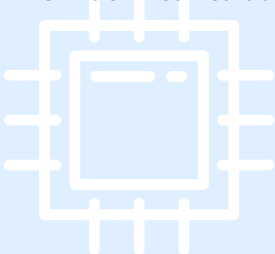
great opportunities for the Company's health sensor products.

The smart home market has also shown a significant growth trend in recent years. According to a report published by China Industry Research Network, driven by continuous empowerment from AI technologies, the market size of China's smart home sector is anticipated to exceed RMB 800 billion by 2025. Such growth provides further potential for the Company's BLE SoC products.

3) Automotive Electronics Sector

With multiple favorable national policies such as vehicle trade-in programs and rural promotion initiatives for new-energy vehicles (NEVs) continuously implemented, the domestic automotive market has witnessed an abundance of new vehicle models released by domestic automotive manufacturers, driving a gradual recovery in automotive consumption in 2024. Meanwhile, China's automotive exports have maintained strong growth momentum. According to data compiled by CAAM from the General Administration of Customs, China's cumulative automotive exports reached approximately USD 233.82 billion in 2024, up by 11.7% year-on-year. This further solidified China's position as the world's leading automotive exporter and created extensive opportunities for upstream component suppliers within the domestic supply chain.

In the major transformation of China's automotive industry, the rapid growth of NEVs plays a crucial role. Throughout 2024, China implemented various favorable policies aimed at consolidating and expanding the existing advantages in NEV development, achieving remarkable results. According to the China Association of CAAM, in 2024, China produced 12.888 million NEVs



and sold 12.866 million units, showing impressive year-on-year growth rates of 34.4% and 35.5%. With the rapid adoption of intelligent driving technology expected in the coming years, demand for semiconductor components such as intelligent cabins, acoustics, and sensors will experience significant growth. Currently, the Company offers

automotive-grade solutions including automotive-grade touch solutions, fingerprint sensors, audio software solutions, automotive-grade BLE SoC products, and continues to broaden its product portfolio. Meanwhile, more products including automotive-grade eSE chips and mid-to-high-power audio solutions are expected to realize commercial adoption in the near future.

3. Major Products During the Reporting Period

(1) Sensor Products

1) Fingerprint Sensors

The Company provides a comprehensive range of fingerprint sensors, including ultrasonic fingerprint sensors, optical in-display fingerprint sensors, and capacitive fingerprint sensors. Its proprietary ultrasonic fingerprint sensor uses CMOS sensor architecture combined with wafer-level acoustic layer processing to achieve a higher signal-to-noise ratio, enabling rapid unlocking even under wet or oily conditions. Additionally, the solution introduced the industry's first sliding enrollment feature globally, delivering greater convenience to users during enrollment. The solution is already being used in over ten mid-to-high-end smartphone models from well-known brands. It has also been integrated into more flagship smartphone projects and is anticipated to see even broader commercial use by 2025.

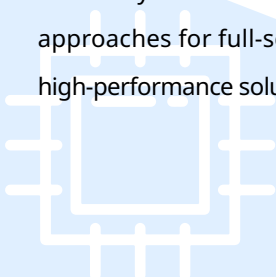
The Company's optical in-display fingerprint sensors represent a pioneering global technology that has effectively led the innovation of biometric recognition approaches for full-screen smartphones, providing high-performance solutions suitable for various smart

devices based on AMOLED screens. Leveraging its technological advantages, this solution continues to maintain a major market share while constantly driving module miniaturization, delivering even more competitive products for customers.

The Company's capacitive fingerprint sensors offer a diverse and extensive product portfolio, including side-mounted, front-mounted, and rear-mounted sensors, addressing numerous application scenarios such as smartphones, PCs/tablets, smart door locks, and automotive electronics. The new generation of ultra-narrow side-key capacitive fingerprint sensors significantly optimizes cost structures while maintaining industry-leading performance, further strengthening their market competitiveness.

2) In-display Light Sensors, Health Sensors and Other Sensors

The Company's in-display light sensors support integrated three-in-one functionality—ambient light sensing, color temperature measurement, and proximity sensing—and can be widely utilized in smartphones, tablets/PCs, wearable devices, and smart home equipment. The latest-generation sensors feature an innovative 2.5D



stacked architecture, modular core components, wafer-level processing, and optimized performance tuning to maximize chip performance. These sensors offer significant performance advantages, including ultra-high sensitivity and ultra-short exposure time, alongside substantially reduced peripheral component costs. They have been effectively integrated into several leading smartphone models from brands like vivo and iQOO. Currently, this solution has been introduced into projects from several brand customers and is expected to further contribute to revenue in 2025.

The Company's health sensor portfolio delivers high accuracy and low power consumption, offering comprehensive measurement functions including heart rate (HR), heart rate variability (HRV), blood oxygen saturation (SpO₂), electrocardiogram (ECG), bioelectrical impedance analysis (BIA), and electrodermal activity (EDA). These sensors can be applied across various product form factors such as smart watches, fitness bands, earbuds, smart rings, and other smart wearable devices. Meanwhile, new and more advanced sensor products have already been successfully adopted in smart watches from prominent brands. Furthermore, as Continuous Glucose Monitoring (CGM) products have gradually gained easier acceptance among diabetes patients, China's domestic CGM market size is expected to steadily expand. In response to this development, the Company has introduced electrochemical analog front-end (AFE) chips characterized by low power consumption, high accuracy, and ultra-compact size, proactively targeting opportunities in the consumer healthcare market.

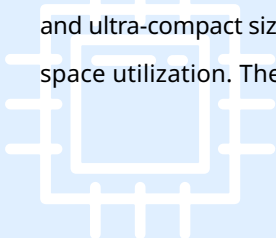
The Company's all-in-one single-chip solutions within VersaSensor feature ultra-low power consumption and ultra-compact size, significantly enhancing device space utilization. These solutions have been widely

applied across various smart wearable devices, including earbuds, smart watches and fitness bands, smart glasses, and other wearable form factors.

(2) Touch Solutions

The Company provides touch solutions in two main categories: consumer-grade and automotive-grade, widely applicable across display-equipped devices within multiple sectors including smartphones, tablets, PCs, automotive electronics, healthcare, and industrial applications. Its consumer-grade product portfolio comprises IC solutions supporting large-, medium-, and small-sized touch screen controllers, touchpad solutions, and active stylus solutions. The automotive-grade product lineup includes touch controller ICs, touch key ICs, and MCUs for touch key products.

Driven by increasing OLED penetration rates in smartphones, the Company's small-sized, high-performance, low-power touch controller ICs with industry-leading features such as high refresh rate support and low latency—have been adopted into flagship projects from renowned global brands including Samsung, Honor, vivo, OPPO, and Xiaomi, delivering consistently growing annual shipments. The new-generation small-sized touch solutions have already been introduced into customers' flagship products and are scheduled for mass production adoption in high-end smartphone models from 2025. Benefiting from the rising penetration rates of capacitive active stylus solutions in smartphones and tablets, the Company achieved sustained growth in shipments of its active stylus products during 2024. Additionally, a new generation of high-performance active stylus products equipped with the Company's self-developed BLE SoC, featuring excellent anti-interference performance, writing experience, and device compatibility, entered mass production in the second half of 2024. Meanwhile,



the integrated solution featuring touch controller ICs, active stylus solutions, and customized protocols has secured a leading market share in the foldable smartphone segment. The Company's touch controller ICs have been widely adopted in flagship models of PCs and tablets, maintaining their leading market position. Furthermore, the Company's Touchpad solutions have secured stable mass-production adoption in flagship PC models from both domestic and internationally renowned brands, due to their strong performance and high reliability.

The Company's automotive-grade touch controller ICs feature high reliability and excellent EMC performance, and are capable of supporting automotive display screens ranging from 5 to over 30 inches. With the recent market launch of vehicle models incorporating its automotive-grade flexible OLED touch controller ICs, the Company has established itself as a leader in this specific market segment. Additionally, the Company's automotive-grade touch key ICs have achieved stable shipments. Meanwhile, its new-generation automotive-grade MCU for touch key products are now under evaluation across multiple customer projects, laying a solid foundation for subsequent mass production and shipments.

(3) Audio Products

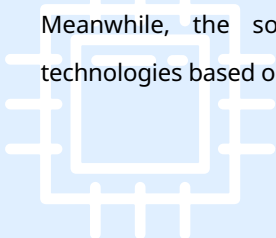
The Company is dedicated to offering integrated hardware-software total solutions that deeply combine hardware and software for AI-enabled audio applications. Its hardware portfolio encompasses a comprehensive product family, ranging from low-power smart audio amplifiers to mid-to-high-power audio amplifier solutions. Meanwhile, the software offering covers core technologies based on deep learning, such as speech

enhancement, call noise reduction, active noise cancellation (ANC/RNC), speech recognition enhancement, and 3D spatial audio capture and playback. These solutions can be widely applied across various application scenarios, including smart devices, automotive, wearables, and IoT.

On the hardware side, the Company's new-generation smart amplifiers, TFA9865 and TFA9864, have entered mass production and have been commercially adopted in high-end smartphone models from brands such as Honor, REDMI, and moto. Commercial adoption is expected to scale further in 2025. Meanwhile, a newly designed architecture for mid-to-high-power audio amplifier products has completed chip-level verification, realizing comprehensive breakthroughs in key performance metrics. These products will be gradually provided as samples to customers and begin commercial adoption throughout 2025. In addition, the development of next-generation low-power smart amplifiers and automotive-grade mid-to-high-power audio products is steadily advancing.

On the algorithm side, the Company's smart amplifiers are equipped with proprietary SpeakBoost algorithms, providing accurate and high-speed current and voltage protection, temperature compensation, and low-pressure compensation protection. Additionally, the unique PowerSave algorithm significantly reduces power consumption while integrating speaker excursion protection and various audio control algorithms, thereby maximizing restoration of original audio source quality.

On the software side, the Company's voice and audio software solutions, including VoiceExperience and AudioCapture, have continued iterative improvements, actively expanding their application into AI-driven voice functionalities (such as call noise reduction and real-time translation), as well as emerging application



scenarios including foldable smartphones, PCs, and XR devices. These solutions have already achieved commercial deployment in models from internationally renowned brands. Looking ahead, the Company plans to continuously enhance user experience by integrating advanced technologies such as deep learning and large-scale AI models.

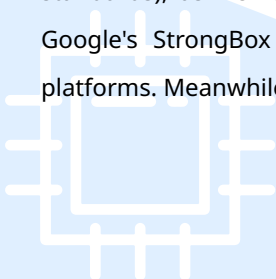
(4) Security Products

The Company's security solutions comprise eSE chips and NFC controller chips, addressing diverse application scenarios such as secure authentication, secure transactions, smart transportation, digital currencies, digital car keys, and digital identities. The new-generation security chips have acquired prestigious domestic and international certifications, including SOGIS CC EAL 6+, OSCCA L2 certification (the highest commercial cryptographic security certification in China), and NPTC (National Financial Technology Certification). The Company's new-generation NFC controller products exhibit outstanding RF performance and compatibility and have been successfully adopted into smartphone models from multiple renowned device brands. Its automotive-grade security chips, which possess the advantages of high security standards, powerful computing capabilities, and concurrent multi-interface support, have achieved international AEC-Q100 certification. These chips incorporate certified operating systems supporting CCC3.0 digital car key applications, enabling Tier-1 automotive suppliers with one-stop solutions. The Company is currently developing new-generation products that will provide leading solutions compliant with both CCC4.0 (international digital car key standard) and ICCE/ICCOA (domestic digital key standards), as well as capabilities compatible with Google's StrongBox solution on mainstream SoC platforms. Meanwhile, the Company will continue to

deepen collaborations across the security ecosystem and explore further innovative applications based on cryptographic technologies.

(5) Wireless Connectivity Products

The Company's wireless connectivity product line primarily consists of BLE SoC products, covering three main application fields: consumer, industrial, and automotive. In the automotive field, the automotive-grade BLE products GR5405 series has achieved mass production shipments for multiple digital car key projects with leading automotive OEMs. Additionally, the Company has established a strategic partnership with United Automotive Electronic Systems Co., Ltd. (UAES) to jointly advance in-depth cooperation on digital car key solutions based on the BLE 6.0 standard. Moreover, the Company is actively progressing on multiple awarded projects with leading automotive OEMs and Tier-1 suppliers, covering application scenarios including digital car keys, T-Box, and in-vehicle connectivity. In industrial and medical sectors, the Company's BLE SoC products have reached mass production in smart metering applications, notably for projects initiated by State Grid Corporation of China and China Southern Power Grid. Additionally, breakthrough achievements were made in the CGM market, with commercial adoption by renowned domestic brands. In the consumer market, the Company's BLE SoC products have continued to achieve market breakthroughs across various areas, human-machine interaction, personal healthcare, smart home, smart display applications, electronic accessories, and smart tracking. Particularly, the Company's solutions currently rank among the top three vendors in China's third-party smart object-finding device market compatible with Apple's "Find My" service.



4. Analysis of Core Competitiveness During the Reporting Period

(1) Outstanding Product Performance and Sustained Innovation Capabilities

The Company is fully committed to advancing four core technology domains: sensing, AI processing, connectivity, and security. Its products include sensors, touch solutions, audio products, security products, and wireless connectivity products, specifically:

The Company's ultrasonic fingerprint sensors, built on proprietary CMOS sensor architecture combined with wafer-level acoustic layer processing technology, deliver higher signal-to-noise ratio (SNR) and incorporate the industry-first sliding enrollment feature, providing users with a more secure, seamless, in-display unlocking experience. This solution significantly optimizes the supply chain process and reduces technical complexity, resulting in strong competitive advantages. Given the accelerating adoption of low-transmittance displays, commercial penetration of ultrasonic fingerprint products is expected to further increase. Meanwhile, the Company continues to maintain its global leadership in both optical in-display fingerprint sensors and capacitive fingerprint sensors. By consistently upgrading technological capabilities and optimizing manufacturing processes, the Company delivers increasingly competitive products.

The Company's touch solutions demonstrate significant advantages, including ultra-high SNR, excellent anti-noise capabilities, ultra-low power consumption, ultra-high report rate exceeding 300Hz, and compatibility with active stylus protocols. The active stylus driver solution supports bidirectional communication and is compatible with various mainstream active stylus protocols. Combined with

high-performance touch control and BLE SoC chips, it provides users with a smooth and precise writing experience. The automotive-grade touch solutions meet the high reliability requirements of the AEC-Q100 standard. Their high refresh rate and unique frequency-hopping technology for improved anti-interference performance fully address international automotive manufacturers' stringent demands for response times and EMC.

The Company's new-generation in-display light sensors adopt an innovative stacked architecture design featuring ultra-sensitive infrared detection capability. Using only one laser emitter, these sensors enable in-display proximity sensing, significantly reducing peripheral component costs. Additionally, the sensors' ultra-short exposure characteristics effectively minimize interference from self-luminous displays on ambient light measurement, enabling high-precision detection even in low-light environments.

The new-generation smart amplifiers, built upon the innovative CoolPWM architecture, incorporate a pure digital path design and an advanced power management mechanism. It achieves the highest output power of 7W in its class and an ultra-low noise floor of less than 7uV, providing louder and clearer sound quality for mobile devices. Equipped with proprietary algorithms including SpeakBoost and PowerSave, the amplifier accurately and rapidly delivers protection functions for temperature and amplitude, significantly reducing power consumption. The Company's voice and audio software solutions will continue to leverage advanced technologies such as deep learning and large-scale AI models, further expanding innovative AI-powered audio applications

and enabling emerging scenarios including foldable smartphones, XR devices, and more.

In 2024, global demand for NFC solutions among mobile device markets continued to increase steadily. Leveraging outstanding RF performance and compatibility, the Company's new-generation NFC products have already been successfully adopted by well-known domestic smartphone brands. Its next-generation security chips have gained multiple high-level authoritative certifications, both domestically and internationally, and have successfully achieved the stringent automotive-grade AEC-Q100 certification, enabling accelerated commercialization of industry-leading digital car key solutions.

The Company's BLE SoC products have achieved breakthroughs in the CGM market, already securing adoption by industry-leading domestic customers, with mass production shipments anticipated in the first half of 2025. Meanwhile, the automotive-grade low-power Bluetooth GR5405 series has successfully entered mass production for multiple digital car key projects with leading automotive OEMs. Moreover, the Company has established a strategic partnership with UAES, to jointly promote in-depth cooperation on digital car key solutions based on the BLE 6.0 standard.

Additionally, the Company's electrochemical AFE chips tailored for the CGM market offer outstanding advantages, including ultra-high precision, ultra-low power consumption, ultra-compact size, and high reliability. These chips can achieve current detection accuracy as high as one-thousandth, while simultaneously supporting temperature measurement and electrode abnormality detection to provide enriched health monitoring capabilities.

(2) First-Class Talent Pool and Robust Technology Reserve

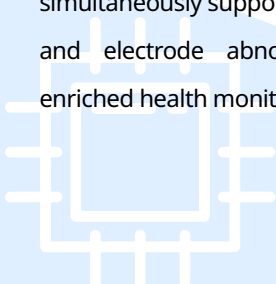
During the reporting period, the Company had approximately 1,400 employees worldwide, with R&D personnel accounting for over 80%, and employees holding master's degrees or higher are more than 50%. The Company's global presence spans across four continents, consisting of 17 research and development centers, technical support centers, and offices. The Company's talent strategy combines external talent recruitment with internal cultivation, aiming to build a robust, professional, and highly skilled global innovation team. Continuous investment in talent development and innovation has accelerated the accumulation of core technologies and related patents. As of December 31, 2024, the Company held an accumulated total of over 7,300 patent applications and granted patents both domestically and internationally.

(3) Long-Term and Stable Supply Chain Collaboration and Comprehensive Inventory Management System

As a fabless integrated circuit design company, the Company is dedicated to chip design and R&D, outsourcing wafer manufacturing, packaging, and testing processes to specialized wafer foundries and packaging/testing suppliers. The selected outsourcing partners are industry-leading international and domestic companies, with whom the Company has established stable long-term strategic partnerships to secure adequate production capacity. These partners flexibly adjust capacity allocation according to changes in industry supply and demand, playing a crucial role in continuously optimizing the Company's comprehensive inventory management system.

(4) Global Strategic Footprint, Brand Influence, and Win Trust Among International and Domestic Customers

The Company has developed an integrated global



innovation R&D network and supply platform, providing differentiated and innovative products and high-quality services to customers worldwide. Its products have been widely adopted by renowned global and domestic brands, such as Samsung, Google, Amazon, Dell, Huawei, OPPO, vivo, Xiaomi, Honor, Lenovo, Transsion, BYD, Hongqi, Geely, GAC, Buick, Honda, Toyota, Hyundai, Nissan, NIO, XPeng, among others.

Through expanding its customer base and leveraging

its rich portfolio of high-quality and differentiated products and services, the Company continues to broaden and deepen cooperation with industry-leading customers in the smart device segment. As the diversification strategy progresses steadily, the application domains of the Company's products now encompass smart devices, IoT, automotive electronics, industrial, and healthcare sectors. This will further extend its customer base, continuously enhance brand recognition in global markets, and enable the implementation of its global strategic vision.

5. Discussion and Analysis on the Company's Future Development

(1) Industry Landscape and Trends

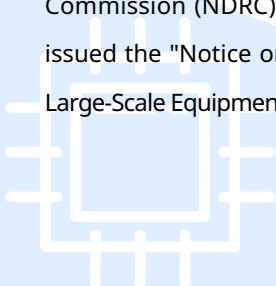
At present, AI and high-performance computing have emerged as significant driving forces for the semiconductor industry. As AI applications become increasingly widespread—from cloud to edge, from consumer to industrial sector, and from security to healthcare—the industry's requirements regarding semiconductor performance, power consumption, and cost continue to rise. Meanwhile, as demand in smartphones, PCs, and infrastructures becomes more stable, the continued growth of the automotive sector is injecting fresh vitality into the semiconductor industry. According to the Semiconductor Industry Association (SIA), driven by global economic recovery and technological advancements, the semiconductor industry's demand will continue to rise, with global chip sales projected to achieve double-digit growth in 2025.

In 2025, China's National Development and Reform Commission (NDRC) and Ministry of Finance jointly issued the "Notice on Expanding and Implementing Large-Scale Equipment Upgrades and Consumer Goods

Trade-In Policies by 2025," aiming to upgrade equipment renewal initiatives and expand support for consumer goods trade-in policies. This will positively stimulate market consumption and substantially boost overall market demand growth. As for specific sectors:

In the smartphone segment, benefiting from government subsidy policies and consumers' device upgrade demands, IDC forecasts that shipments of Android smartphones in the China market will record a year-on-year increase of 5.6% in 2025. Additionally, continuous optimization in both hardware and software, coupled with declining costs, has been driving the growing penetration of OLED displays in smartphones. Omdia forecasts that the global penetration rate of OLED-equipped smartphones is expected to reach 60% by 2028, corresponding to estimated shipments of approximately 750 million units.

Ongoing expansion in the smartphone market and sustained penetration of OLED screens will create



greater opportunities for growth in the Company's various product lines, including fingerprint sensors, touch and active stylus solutions, smart amplifiers and audio software, in-display light sensors, and NFC/eSE products, etc.

In the PC and tablet sectors, the following trends are expected to emerge:

1) AI-enabled PCs, characterized by innovative smart experiences, may stimulate a new wave of device upgrades among consumers. In addition, along with the continued expansion of Chinese home appliance and consumer electronics exports, domestic tablet and PC markets are anticipated to experience greater growth in 2025.

2) A new form has emerged, and foldable PCs and tablets might become a reality, representing the next wave of innovative application scenarios following foldable smartphones. The recovery and growth in demand for PCs and tablets will create expanded market opportunities for the Company's various product offerings, including fingerprint sensors, touch solutions, audio products, and in-display light sensors.

In the wearable device sector, smartwatches, fitness bands, and other wearable devices are expected to integrate deeply with AI technologies, delivering highly personalized user experiences. The health monitoring features will undergo upgrades, making blood pressure and blood glucose monitoring functions increasingly mature and widespread, along with the emergence of additional early screening functionalities for specific diseases. Emerging markets such as smart glasses are expected to gain prominence, incorporating innovative features including intelligent translation, information alerts, and health monitoring. Meanwhile, device manufacturers will place greater emphasis on data security and privacy

protection, employing advanced encryption technologies to ensure the confidentiality and security of user data and privacy. The aforementioned developments in the wearable device sector are expected to generate expanded market opportunities for the Company's next-generation health sensors (such as PPG AFE and multi-modal AFE solutions), audio products, NFC/eSE solutions, and in-display light sensors.

In the IoT sector, substantial market opportunities and promising development prospects lie ahead in various application fields, including industrial IoT, smart homes, intelligent driving, and smart cities. Correspondingly, the Company's touch solutions, audio products, Bluetooth Low Energy (BLE) SoC products, and in-display light sensors will continue to undergo iteration and upgrades, expanding into more innovative application scenarios.

In the automotive electronics sector, intensified market competition combined with scaled-up production has led to declining prices for electric vehicles, driving exponential growth in electric vehicle (EV) demand. According to automotive research firm Rho Motion, global EV sales are projected to exceed 20 million units by 2025. With the rapid advancement of automotive intelligence, trends toward larger and multiple in-vehicle displays are driving upgrades in automotive audio-visual experiences and smart voice interactions. Meanwhile, the replacement of traditional car keys with digital car keys is also accelerating. These industry developments are expected to create new business opportunities for the Company's automotive-grade touch solutions, audio products, and BLE SoC products.

In the robotics sector, applications span widely across various markets, including industrial, medical,

agricultural, and home scenarios. Among these, smart home robots utilize voice recognition and human-machine interaction technologies to enable automatic control and intelligent management of household devices, creating a more comfortable and convenient living environment for users. The Company's product offerings, including touch solutions, in-display light sensors, BLE SoC products, and audio products, support such smart home robot applications.

In the VR/AR field, Counterpoint forecasts that global shipments of extended reality (XR) glasses will exceed 105 million units by 2025. Among these, the AR + AI glasses market, demonstrating strong growth potential, is expected to experience accelerated expansion in 2025. With continuous enhancement in product functionalities, virtual reality (AR/VR/XR) glasses are regarded as next-generation interactive terminals featuring substantial demand for various types of sensors. Such developments are expected to generate greater potential opportunities for the Company's product lines, covering in-display light sensors, audio products, BLE SoC products, and VersaSensor.

(2) Corporate Development Strategy

The Company adheres to the corporate mission, "Enrich Your Life Through Innovation." Leveraging a global vision and strategic presence, the Company gathers top global talents, maintains unwavering investment in R&D, and continuously leads technological innovations across the domains of sensing, AI processing, connectivity and security. The Company aims to enable innovative applications with intelligent connectivity of all things, striving to become a world-leading comprehensive IC design enterprise. In doing so, it seeks to create greater and differentiated value for global customers and partners,

enriching billions of consumers' intelligent lifestyles worldwide.

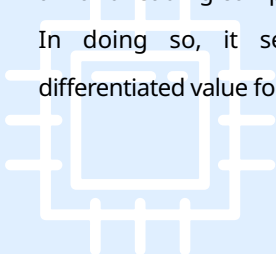
To achieve these goals, the Company is committed to continuously investing in R&D, diversifying product categories, enhancing product competitiveness, and accelerating product iteration, thereby maintaining leadership in niche markets. The Company will further enhance its management and operational efficiency, establish robust integrated capabilities and a sound financial foundation to better respond to external environmental uncertainties.

Moreover, the Company plans to intensify its market promotion efforts, formulate new product strategies based on deep insights into customer demands, rigorous strategic planning, and evaluations, and further enrich product application scenarios. Continuous efforts will go into segments such as smart devices, IoT, automotive electronics, industrial markets, and other emerging fields.

In addition, the Company will proactively engage in industrial expansion strategies through mergers, acquisitions, and other capital market operations targeting high-quality assets that align with the Company's strategic orientation. These actions aim to rapidly enhance the Company's competitive advantages and innovation capabilities, fully pursue performance improvement, capability enhancement, and new business expansions, and establish a virtuous cycle of growth. Ultimately, the Company seeks to achieve high-quality, robust, and sustainable development, creating greater value for society and shareholders.

(3) Business Plan

The Company will continue adhering to the corporate development strategy, firmly commit to independent innovation, sustained investment in R&D, and promotion



of original intellectual property creation and application. The Company will maintain the core advantages of existing products while accelerating market penetration of new products. At the same time, it will deepen business relationships with smart device customers and continue to expand market share.

Through innovative enterprise management approaches, the Company will improve organizational capabilities, increase operational efficiency, and enhance overall product competitiveness. The Company will also strongly emphasize developing a highly competent technical team, establishing a solid foundation for future new product innovations.

Furthermore, the Company will accelerate AI-enabled management by adopting intelligent and digital technologies, thereby supporting comprehensive corporate development. In addition, the Company plans to actively pursue capital operations, including mergers and acquisitions, to further strengthen the integrated capabilities and market competitiveness.

1) Maintain Core Advantages in Existing Products and Accelerate Penetration of New Products

Fingerprint sensors and touch solutions, as the primary sources of the Company's revenue, have consistently maintained leading market positions. In 2025, the Company will continue product iterations, aiming to enhance performance, optimize costs, maintain the core competitive advantages, and expand opportunities into additional commercial scenarios.

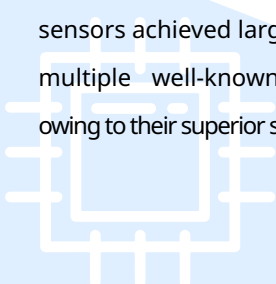
During the reporting period, ultrasonic fingerprint sensors achieved large-scale commercial adoption in multiple well-known terminal brand customers, owing to their superior signal-to-noise ratio and recognition

performance. In 2025, the Company plans to introduce these sensors to a wider range of customers and additional smartphone terminal projects. Additionally, the newly launched smart amplifiers successfully entered mass production with various mainstream terminal brands. Moreover, new-generation in-display light sensors and NFC/eSE products have also been scaled for commercial adoption in flagship smartphone customer projects in the fourth quarter. The Company plans to further intensify promotion efforts and expand adoption across more customers and projects in 2025, thus becoming key growth engines for future business.

2) Deepen Relationships with Smart Device Customers and Further Expand Market Share

The Company's customer base primarily spans multiple fields including smart devices, IoT, automotive electronics, and industrial sectors. As the Company expands the number and range of products delivered within individual customer terminals, it creates increased value through potential synergies for customers. Alongside accelerated introduction of innovative new products, it is essential to further strengthen the depth of cooperation with customers. By deeply analyzing the demands and pain points of leading customers, jointly developing strategic projects, and offering tailored solutions, the Company helps customers differentiate their products, thus continuously expanding the market share.

For overseas business expansion, the Company will prioritize enhancing customer support, raising service levels and delivery capabilities, and building more specialized service teams, thereby improving its penetration into high-end device projects with key international clients. Concurrently, the Company will sustain strategic investments targeting customers



where it has yet to achieve breakthroughs, aiming for early successes. These efforts are intended to solidify its global customer base and further increase company revenues and profitability.

3) Enhance Organizational Capability and Operational Efficiency to Enhance Product Competitiveness

The Company will continue to refine its internal management system by implementing a customer-driven integrated product development process. This effort will effectively integrate core operational processes, including market demand analysis, product development, technical support, production management, quality control, and financial management, ensuring seamless connectivity among all these sections. Additionally, the management system will be upgraded towards an automated management platform to enhance overall operational efficiency.

Through improvements in the quality management framework, the Company will optimize processes ranging from product design and manufacturing to mass production quality management and outsourced supplier evaluation and oversight, allowing for prompt identification and resolution of potential issues to consistently deliver high-quality products to customers.

The Company will also continuously optimize the inventory management, establish a robust and reliable supply chain system, and strengthen communication with long-term suppliers. Under the assurance of stringent product quality, partial production outsourcing will shift to domestic manufacturing partners, thus ensuring stable capacity supply while effectively managing production costs. These initiatives are expected to further enhance product competitiveness and meet

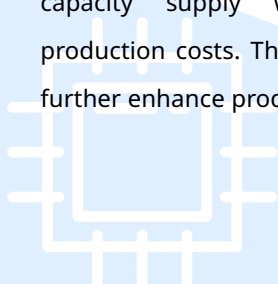
diverse global customer demands.

4) Strengthen Talent Development and Enhance Team Collaboration Capabilities

In talent development, the Company provides diversified training opportunities and an extensive platform for staff to showcase their skills and potential. Regarding talent incentives, the Company has established a dual-track career advancement mechanism in both managerial and technical paths, offering staff diversified career development avenues. Additionally, the Company implements various long-term incentive measures intended to foster shared interests between staff and the Company, thus building robust internal cohesion. Meanwhile, the Company has established multi-dimensional communication mechanisms to promote cross-cultural collaboration and communication, continuously enhancing global teamwork efficiency and operational capabilities.

5) Accelerate AI-Enabled Management to Facilitate Comprehensive Corporate Development

The Company proactively develops and deploys AI technologies to streamline internal processes, drive process automation, reduce labor costs, and improve interdepartmental collaboration efficiency. By continuously introducing advanced AI technologies and large-scale AI models, the Company is accelerating the R&D progress and enhancing overall competitiveness. Meanwhile, the Company aims to popularize AI assistant tools internally to boost staff work efficiency, actively exploring innovative potentials in AI application areas. Leveraging deep learning methodologies and AI-enabled tools, the Company will conduct information collection and big data analysis to identify and mitigate potential risks, thus providing comprehensive support for its strategic development.



6. Key Accounting Data and Financial Indicators

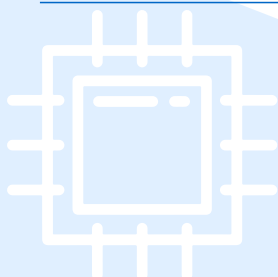
Shenzhen Goodix Technology Co., Ltd.

Consolidated Income Statement

For the twelve months ended Dec 31,2024 and Dec 31,2023

(The currency of the statement is Chinese Yuan,'CNY',unless otherwise indicated)

Items	Jan-Dec,2024	Jan-Dec,2023
1. Revenue	4,374,948,942.73	4,408,052,320.27
Less: Operating cost	2,546,541,807.60	2,624,385,941.66
Taxes and surcharges	32,112,225.11	28,776,418.12
Selling expenses	190,126,010.76	217,733,298.39
General and administrative expenses	177,327,629.35	211,583,428.42
Research and development expenses	949,987,699.44	1,049,255,196.17
Finance expenses	-104,178,618.82	-83,824,893.06
Including: Interest expense	13,553,813.49	21,792,653.69
Interest income	112,398,924.05	97,791,855.53
Add: Other income	76,681,094.26	92,948,231.37
Investment income	28,463,624.52	24,391,145.06
Including: Investment income from joint ventures and affiliates		
Earning from fair market value changes	-9,304,023.90	-21,120,870.76
Impairment of credit	342,752.74	-1,568,438.42
Impairment of assets	-15,244,735.27	-376,260,742.16
Proceeds from asset disposal	3,804,070.32	1,851,833.26
2. Operating profits	667,774,971.96	80,384,088.92
Add: non-operating income	358,815.67	1,889,638.22
Less: non-operating expenses	176,489.27	8,038,860.07
3. Profit before tax	667,957,298.36	74,234,867.07
Less: income tax	64,258,263.49	-90,815,657.63
4. Net profit	603,699,034.87	165,050,524.70
5. Other comprehensive income after tax	18,512,635.29	43,834,089.22
6. Total comprehensive income	622,211,670.16	208,884,613.92
7. Earning per share:		
I .Basic earnings per share	1.33	0.36
II .Diluted earning per share	1.32	0.36



Consolidated Statement of Balance Sheet

As of Dec 31, 2024 and Dec 31, 2023

(The currency of the statement is Chinese Yuan, 'CNY', unless otherwise indicated)

Assets	31-Dec-24	31-Dec-23
Current assets:		
Cash and cash equivalents	3,479,681,529.31	3,068,039,907.00
Financial assets held for trading	1,304,717,700.63	953,344,772.91
Notes receivables and trade receivables, net	515,730,672.67	618,707,224.57
Receivables financing	4,822,795.50	9,549,729.89
Inventories	569,689,205.85	715,878,757.52
Prepayments	24,826,163.75	6,201,885.71
Other receivables	78,860,332.88	50,455,238.26
Assets held for sale	285,627,354.52	
Current portion of non-current assets	60,596,753.49	74,974,511.72
Other current assets	252,073,840.33	55,653,509.37
Total current assets	6,576,626,348.93	5,552,805,536.95
Non-current assets:		
Long-term equity investments		
Investments in other equity instruments	3,146,000.00	
Other non-current financial assets	184,149,154.57	205,682,076.74
Investment property	190,627,174.81	47,765,556.29
Property, plant and equipment	693,348,110.40	333,178,494.37
Construction in progress		474,669,742.76
Right-of-use assets	31,284,775.46	55,617,961.76
Intangible assets	1,189,197,128.35	1,122,301,026.83
Development costs	355,579,322.52	532,973,053.89
Goodwill	401,554,695.66	511,650,301.26
Long-term deferred expenses	6,858,393.87	9,902,670.34
Deferred tax assets	545,009,381.93	585,436,948.62
Other non-current assets	126,957,146.95	295,047,610.13
Total non-current assets	3,727,711,284.52	4,174,225,442.99
Total assets	10,304,337,633.45	9,727,030,979.94

Liabilities and Stockholders' Equity	31-Dec-24	31-Dec-23
Current liabilities:		
Short-term loans	185,129,555.56	211,191,492.29
Financial liabilities held for trading	606,757.46	
Notes payables and trade payables	320,367,579.21	402,087,092.95
Advances from customers	3,101,372.36	4,433,668.73

Contract liability	13,432,125.67	7,423,261.42
Accrued payroll	270,858,079.63	289,934,449.33
Taxes payable	23,255,440.41	38,416,296.25
Other payables	403,437,071.00	342,828,460.40
Liabilities held for sale	46,072,918.64	
Current portion of non-current liabilities	20,410,197.35	28,783,548.96
Other current liabilities	1,533,281.31	180,081.70
Total current liabilities	1,288,204,378.60	1,325,278,352.03
Non-current liabilities:		
Long-term loans	237,098,022.62	242,089,559.96
Lease liabilities	18,122,114.27	34,799,266.18
Accrued liabilities		
Deferred income	11,127,718.99	12,713,990.33
Deferred tax liabilities	28,288,865.15	66,869,217.48
Total non-current liabilities	294,636,721.03	356,472,033.95
Total liabilities	1,582,841,099.63	1,681,750,385.98
Equity:		
Paid-in capital	461,865,256.00	458,001,914.00
Additional Paid-in capital	1,969,904,214.76	1,559,406,572.12
Less: treasury shares	341,810,958.92	63,659,662.15
Other comprehensive income	22,377,344.80	3,864,709.51
Retained earnings	6,609,159,105.11	6,087,666,220.51
Equity attributable to owners of the parent company	8,721,494,961.75	8,045,279,753.99
Equity attributable to minority shareholders	1,572.07	839.97
Total stockholders' equity	8,721,496,533.82	8,045,280,593.96
Total liabilities and stockholders' equity	10,304,337,633.45	9,727,030,979.94

Consolidated Statement of Cash Flows

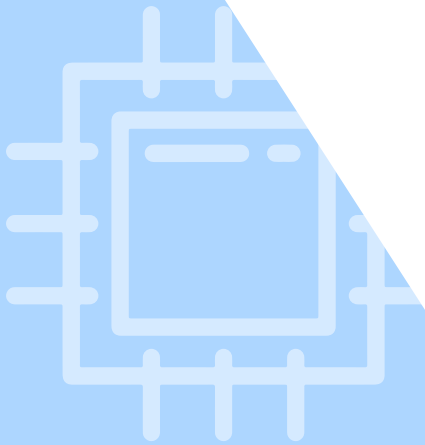
For the twelve months ended Dec 31,2024 and Dec 31,2023

(The currency of the statement is Chinese Yuan,'CNY',unless otherwise indicated)

Items	Jan-Dec,2024	Jan-Dec,2023
1.Cash flows from operating activities		
Cash received from sales and services	4,828,187,305.64	4,583,535,962.09
Taxes and surcharges refunds	111,035,310.28	219,704,470.87
Other cash received from operating activities	138,203,837.88	168,409,101.21
Total cash inflows from operating activities	5,077,426,453.80	4,971,649,534.17
Cash paid for goods and services	2,562,894,696.84	1,574,228,524.70
Cash paid for employees related expenses	901,742,991.28	996,273,979.46

Taxes and surcharges cash payments	167,490,013.45	187,834,376.80
Other cash payments related to operating activities	372,625,689.45	427,541,915.76
Total cash outflows from operating activities	4,004,753,391.02	3,185,878,796.72
Net Cash generated from operating activities	1,072,673,062.78	1,785,770,737.45
2.Cash flows from investing activities		
Cash received from withdraw of investments	2,163,198,397.00	1,265,204,443.19
Cash received from investment income	32,766,696.52	8,746,242.91
Net cash received from disposal of fixed assets, intangible assets and other long-term assets	3,994,566.62	357,419.18
Net cash received from disposal of subsidiaries and other business units		
Cash received from other investment related activities		
Total cash inflows from investing activities	2,199,959,660.14	1,274,308,105.28
Cash paid for fixed assets, intangible assets and other long-term assets	230,814,719.54	433,826,348.46
Cash payments for investments	2,987,094,058.17	2,568,695,835.93
Cash paid for other investment related activities		1,140.00
Net cash payments for acquisitions of subsidiaries and other business units		
Total cash outflows from investing activities	3,217,908,777.71	3,002,523,324.39
Net cash used in investing activities	-1,017,949,117.57	-1,728,215,219.11
3.Cash flows from financing activities		
Cash received from investments by others including: investment from minority shareholders	222,784,357.54	114,765,428.89
Cash received from borrowings	385,000,000.00	460,576,865.97
Other cash received from other financing activities	2,000,549.07	78,573,936.18
Total cash inflows from financing activities	609,784,906.61	653,916,231.04
Cash repayments for debts	415,991,537.34	734,219,036.88
Cash payments for distribution of dividends,profit and interest expenses	96,443,437.51	18,590,707.79
Other cash payments related to financing activities	90,110,824.38	210,797,156.62
Total cash outflows from financing activities	602,545,799.23	963,606,901.29
Net cash provided by financing activities	7,239,107.38	-309,690,670.25
4.Effect of changes in exchange rate on cash and cash equivalents	11,808,493.18	13,692,106.64
5.Net increase in cash and cash equivalents	73,771,545.77	-238,443,045.27
Add: Cash and cash equivalents at the beginning of the year	828,831,789.19	1,067,274,834.46
6.Cash and cash equivalents at the end of the year	902,603,334.96	828,831,789.19

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